Update Project Proposal: SFF-TA-1008 (E3 specification)

Presented: 2025-09-26

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Supporters: Paul Kaler [HPE], Mike Gregoire [Dell], John Geldman [Kioxia], Pardeep Bhatti [Sandisk], Wayne Gregory [Solidigm]

Original Project Proposal: SFF-TA-1008 R2.1 (E3)

- Purpose: Update the following:
  - The Power/Thermal Requirements Section to clarify power capabilities to align with connector limits
  - Template update
  - Removal of secondary grounding strip
- Editor(s):
  - SFF-TA-1008: Paul Kaler, Mike Gregoire
- Supporters:
  1. Dell
  2. HPE
  3. Kioxia
  4. Micron
  5. Sandisk

Revised Project Proposal: SFF-TA-1008 R2.1 (E3)

- Purpose: Update the following:
  - The Power/Thermal Requirements Section to clarify power capabilities to align with connector limits
  - Template update
  - Removal of secondary grounding strip
  - Amend E3.S 1T and E3.L 1T for thermal contact cooling and air cooling support
- Editor(s):
  - SFF-TA-1008: Paul Kaler, Mike Gregoire
- Supporters:
  1. Dell
  2. HPE
  3. Micron
  4. Kioxia
  5. Sandisk
  6. Solidigm

Proposed Thermal Contact Cooling changes

- Thermal contact cooling surfaces highlighted
- Other changes as needed relating to this.

Thank You

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